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MOV



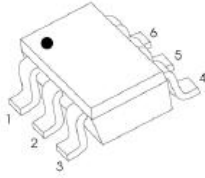
GDT



PLED

Product data sheet
Product data sheet

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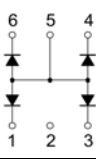
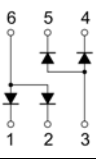
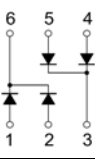
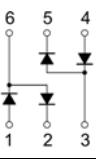





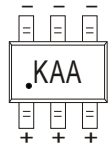


SOT-363

Switching Diode

FEATURES

- Fast Switching Speed
- Ultra-Small Surface Mount Package
- For General Purpose Switching Applications
- High Conductance Power Dissipation

MMBD4448HAEW	MMBD4448HADW	MMBD4448HCDW	MMBD4448HSDW	MMBD4448HTW
				
MARKING:KA5	MARKING:KA6	MARKING:KA7	MARKING:KAB	MARKING:KAA
				

Solid dot = Pin1 indicate.

Solid dot = Green molding compound device, if none, the normal device.

Maximum Ratings and Electrical Characteristics, Single Diode @T_a=25 °C

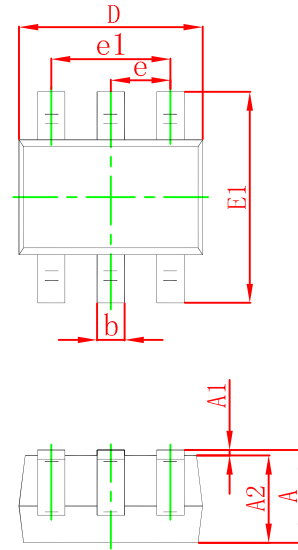
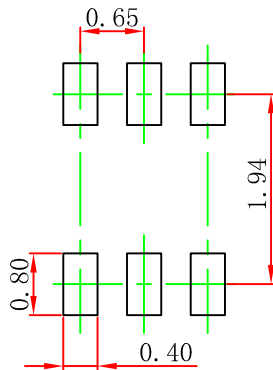
Parameter	Symbol	Limit	Unit
Non-Repetitive Peak Reverse Voltage	V _{RM}	100	V
Peak Repetitive Peak Reverse Voltage	V _{RRM}	80	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	57	V
Forward Continuous Current	I _{FM}	500	mA
Average Rectified Output Current	I _O	250	mA
Non-Repetitive Peak Forward Surge Current @t=8.3ms	I _{FSM}	2.0	A
Power Dissipation	P _d	200	mW
Thermal Resistance from Junction to Ambient	R _{θJA}	625	°C/W
Storage Temperature	T _{STG}	-55 ~+150	°C

ELECTRICAL CHARACTERISTICS

Electrical Ratings @Ta=25°C

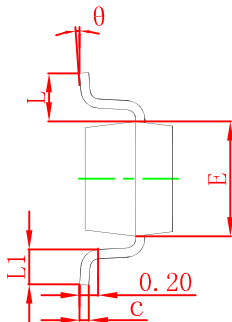
Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Reverse Breakdown Voltage	$V_{(BR)}$	80			V	$I_R=100\mu A$
Forward Voltage	V_{F1}	0.62		0.72	V	$I_F=5mA$
	V_{F2}			0.855	V	$I_F=10mA$
	V_{F3}			1.0	V	$I_F=100mA$
	V_{F4}			1.25	V	$I_F=150mA$
Reverse Current	I_{R1}			100	nA	$V_R=70V$
	I_{R2}			25	nA	$V_R=20V$
Capacitance Between Terminals	C_T			3.5	pF	$V_R=0V, f=1MHz$
Reverse Recovery Time	t_{rr}			4	ns	$I_F=I_R=10mA$ $I_{rr}=0.1I_R, R_L=100\Omega$

SOT-363



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
c	0.100	0.150	0.004	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.400	0.085	0.094
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

REEL SPECIFICATION

P/N	PKG	QTY
MMBD4448	SOT-363	3000

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